


MATERIAL DECLARATION SHEET



Package Type	CDSOT23 (CDSOT23-T24CAN)			
Product Line	Semiconductor Products			
Compliance Date	July 29, 2022			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.00532315	Amorphous Silica	60676-86-0	87.600	48.2794	51.8624
				Epoxy Resin A	Proprietary	4.900	1.3335	
				Epoxy Resin B	29690-82-2	4.000	1.2010	
				Phenol Resin	Proprietary	3.000	0.8164	
				Carbon Black	1333-86-4	0.500	0.2320	
2	Leadframe	Copper Alloy	0.00394239	Copper	7440-50-8	97.100	37.3806	38.4098
				Iron	7439-89-6	2.289	0.7747	
				Phosphorus	7723-14-0	0.020	0.0016	
				Zinc	7440-66-6	0.100	0.0306	
				Lead	7439-92-1	0.010	0.0049	
3	Chip	Silicon	0.00051653	Silver	7440-22-4	0.481	0.2175	5.03245
				Silicon	7440-21-3	91.032	4.5811	
				Nickel	7440-02-0	6.091	0.3065	
				Aluminum	7429-90-5	2.500	0.1258	
4	Die Attach	Silver Epoxy	0.00021947	Gold	7440-57-5	0.377	0.0190	2.13823
				Silver	7440-22-4	75.000	1.9192	
				Epoxy resin	9003-36-5	19.900	0.1913	
				1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	3.000	0.0081	
				Aromatic polyamine	Proprietary	2.000	0.0193	
5	Bond Wires	Copper	0.00002397	Adipic acid	124-04-9	0.100	0.0003	0.23352
				Copper	7440-50-8	98.700	0.2295	
6	Lead Finish	Matte Tin	0.00023850	Non - Cu element	Proprietary	1.300	0.0041	2.3236
				Tin	7440-31-5	100.000	2.3236	
		Total Weight	0.01026401					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.